Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	22486	semiconductor adj package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/10/03 07:27
L2	21415	pre$cut	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/10/03 07:27
L3	1033	wafer adj grinding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/10/03 07:28
L4	1219	dicing adj tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/10/03 07:28
L5	1	1 and 2 and 3 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/10/03 07:29
L6	30	1 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/10/03 07:31
L7	1	2 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/10/03 07:29
L8	85	1 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/10/03 07:31
L9	5	8 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/10/03 07:32
L10	2	("5241133" | "5886949").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:34

L11	532	29/25.01.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:34
L12	3	9 and 1 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:40
L13	260	29/729.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:40
L14	0	13 and 1 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:40
L15	1317	29/827.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:42
L16	1	15 and 1 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:43
L17	292	29/742.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:43
L18	0	17 and 1 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:43
L19	693	438/462.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:43
L20	10	19 and 1 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:45
L21	234512	grind$3	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:45
L22	34	21 and 1 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:48
L23	1	21 and 1 and 2 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:48
L24	34	21 and 1 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:49
L25	118845	back adj side	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:50
L26	24	1 and 21 and 25 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:52

L27	0	438/464.ccls	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:53
L28	709	438/458.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:53
L29	1	28 and 1 and 2 and 4 and 21	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:54
L30	13	1 and 2 and 21 and 25	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:57
L31	8	1 and 3 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:58
L32	386211	tape	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:58
L33	5	1 and 2 and 21 and 25 and 32	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 08:00
L34	15	("20010004002" | "5645787" | "5998243" | "6001672" | "6021380" | "6052798" | "6090644" | "6106259" | "6111324" | "6117382" | "6192457" | "6268641" | "6391666" | "6415977" | "6555400").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 07:59
L35	13	1 and 2 and 21 and 25	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 08:13
L36	3	1 and 2 and 4	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 08:13
L37	0	"6271102".ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 08:14
L38	1	"6271102".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 08:16
L39	0	semiconductor with pre-cut with dicing with tape with grinding	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 08:18
L40	1	semiconductor with pre-cut with dicing with tape	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 08:18
L41	1	semiconductor with package with pre-cut with dicing	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/03 08:19